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# Datasheet

## NEXCOM

### NDiS B360

Fanless Embedded Computer with 11th Gen. Intel® Core™ Tiger Lake UP3 Processor



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## Main Features

- 11th Generation Intel® Core™ (Tiger Lake-UP3) processor SoC
- Dual 4K @ 60Hz display output, DP++, HDMI 2.0
- Support 4K @ 60Hz eDP display output
- Dual LAN ports and 4 x USB 3.0 ports for easy connection
- Compact and slim design (H: 36mm)
- Onboard M.2 2280 Key M with PCIe signal for storage modules
- Onboard M.2 2230 Key E for optional Wi-Fi modules
- Support extended temperature for outdoor application
- Fanless design

## Product Overview

Powered by the latest 11th generation Intel® Core™ Tiger Lake processor, NDiS B360 series digital signage player can handle very rich multimedia contents. With Intel® processor low power consumption and new Intel® Iris® Xe graphics, the platform deliver powerful graphics offering stunning visuals for compelling 4K content creation and media playback. In addition, NDiS B360 series supports display output by HDMI and DP ports with flexible integration for various peripherals such as touchscreen displays, scanners, readers, and many more. NDiS B360 series is a slim/fanless player with extended temperature durability further extends to outdoor usage like QSR drive through kiosks, box office displays, information stands, bus stops, or digital transit information signs. It is also ideal as a digital signage player delivering enhanced performance and new immersive experiences for advertising, hospitality and brand promotion applications.

## Specifications

### CPU Support

- Onboard 11th Generation Intel® Core™ i3-1115G4E processor, Dual Core, 2.2 GHz, 6M Cache (15W)
- Onboard 11th Generation Intel® Core™ i5-1145G7E processor, Quad Core, 1.5 GHz, 8M Cache (15W)
- Onboard 11th Generation Intel® Core™ i7-1185G7E processor Quad Core, 1.8 GHz, 12M Cache (15W) (by request)

### Chipset

- SoC (codenamed Tiger Lake-UP3)

### Main Memory

- 1 x 260-pin DDR4 SO-DIMM, supports non-ECC, un-buffered memory up to 32G

### Graphics & Display

- Intel® UHD graphics on i3 processor
- Intel® Iris® Xe graphics on i5 and i7 processor
- 1 x DP++, support 4096 x 2304 @ 60Hz
- 1 x HDMI 2.0, support 4096 x 2160 @ 60Hz

### I/O Interface-Front

- 1 x Power button
- 1 x HDD LED

- 1 x Line-out
- 1 x DB9 for RS232 (COM2)
- 2 x Antenna hole

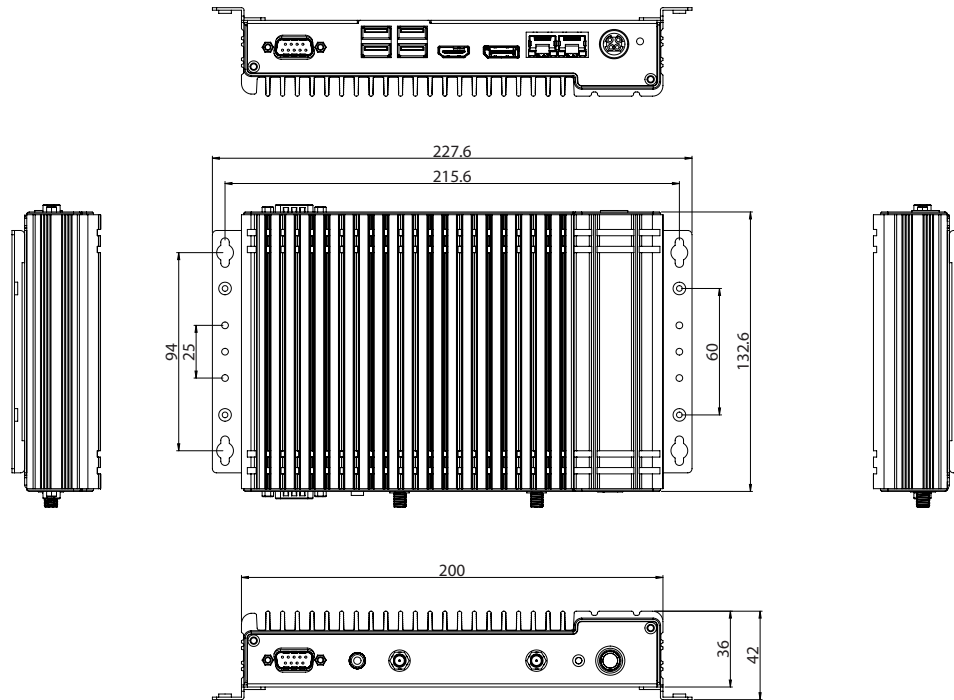
### I/O Interface-Rear

- 1 x 12V DC Jack
- 2 x RJ45 Intel® Gigabit LAN port
  - 1 x Intel® I219-LM GbE PHY
  - 1 x Intel® I211-AT GbE LAN
- 1 x DP++
- 1 x HDMI 2.0
- 4 x USB 3.0
- 1 x DB9 for RS232/422/485 (COM1)

### I/O Interface-Internal

- 4 x USB 2.0, internal connector
- 1 x Mic-in, internal connector
- 1 x Speaker-out with 2W/4Ω amplifier, internal connector
- 6 x GPIO pin header for 3 x GPI and 3 x GPO
- 1 x 4-pin connector for PWM smart FAN
- 1 x 12V 2A power output coming from main power source to additional module use
- 1 x eDP: support 4096 x 2160 @ 60Hz
- TPM 2.0 onboard

## Dimension Drawing



### Storage

- 1 x M.2 2280 Key M (PCIe x4 only), support optional storage modules

### Expansion

- 1 x M.2 2230 Key E (PCIe x1), support optional Wi-Fi modules

### Power Supply

- 1 x External 60W AC/DC power adapter
- Input: 100VAC to 240VAC
- Output: DC+12VDC

### Environment

- Operating temperature: -20°C to 60°C
- Storage temperature: -20°C to 80°C
- Humidity: 10 to 90% (non-condensing)

### Certification

- CE Approval
- FCC Class A

### Dimensions

- 200mm (W) x 132.6mm (D) x 36mm (H) (without wall mount bracket)

### Operating System

- Win10/Linux

## Ordering Information

- **NDiS B360-i3 (P/N: 10W00B36000X0)**  
11th Generation Intel® Core™ i3-1115G4E processor slim and fanless system
- **NDiS B360-i5 (P/N: 10W00B36001X0)**  
11th Generation Intel® Core™ i5-1145G7E processor slim and fanless system

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